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|-------------------|--|
| Under Development | |
| Mass production | |



Client Name

Client P/N

Product P/N

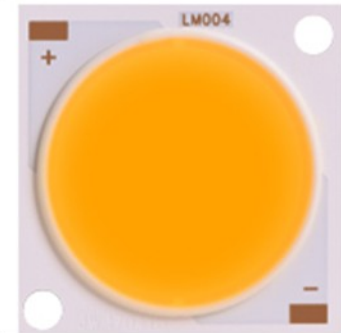
Sending Date:

| | | | | |
|-----------|--------------|----------|-------|--------------|
| | | | | |
| Approval | Audit | Approval | Audit | Confirmation |
| | | | | |
| Qualified | Disqualified | DATE: | | |

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LM 004 H384 W - 25 B12 C12 (Ra2)



Product line code

Chip code

Recommend the minimum



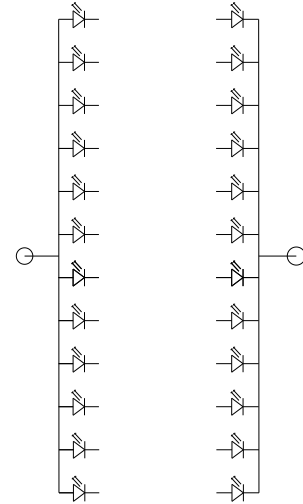
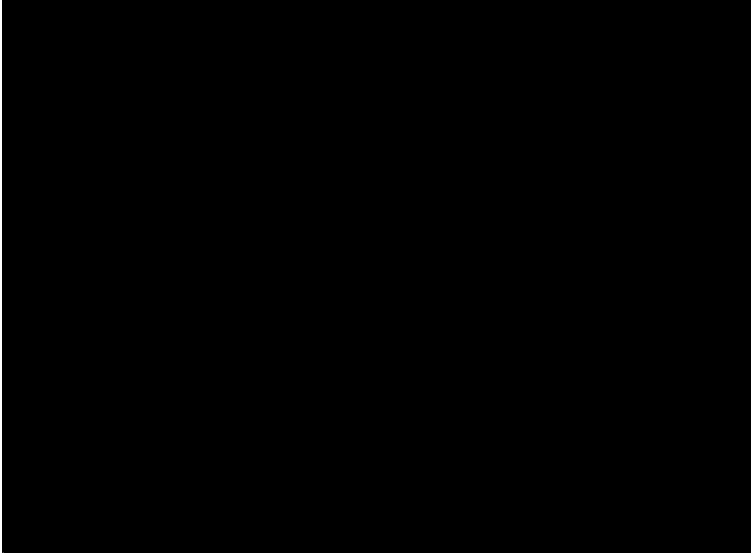
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

The number of parallel

The number of series

- Dimension 28.0mm×28.0mm×1.6mm
28.0mm×28.0mm×1.6mm
- CRI: Ra 80 80
- Wide viewing angle : 120° 120°
- RoHS compliant ROHS
- sulphation corrosion resistance
- Manual Soldering

- Down light
- Spot light



Tolerance unless otherwise specified: $\pm 0.3\text{mm}$.
 ± 0.3

| | | | | | |
|-----------------------------|------------------|------------------------|------|------|----|
| | | | | | |
| Input power range | Pi | 24.5 | 38.3 | 68.4 | W |
| operating current range | IF | 720 | 1050 | 1800 | mA |
| | | | | | |
| Junction Temperature | Tj | 120 | | | °C |
| Operating Temperature Range | Top | -35 °C To +85 °C | | | |
| Storage Temperature Range | Tstg | -40 °C To +85 °C | | | |
| Lead Soldering Temperature* | T _{SOL} | Max. 350 for 5sec Max. | | | |

Notes for Table:

1. The temperature of Aluminum PCB do not exceed **85** If the input power reach 80% max Pi, the temperature of Aluminum PCB should be control below **75**

85

80%

75 免

2. When hand soldering, keep the temperature of iron below less **350 less than 5seconds**

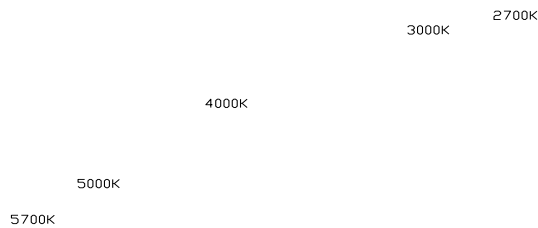
350 ,

5

3. D.C. Current : $T_j = T_s + R_j \cdot s \times P_i$



| | | | | | | | |
|--|---|--------------|------|------|------|-----|----|
| | | | | | | | |
| | | IF=1050mA | 34 | 36 | 40 | — | V |
| | Φ | TC=2700K | 4250 | 4470 | 4850 | 119 | Lm |
| | | TC=3000K | 4400 | 4700 | 5100 | 123 | |
| | | TC=3500K | 4600 | 4900 | 5300 | 128 | |
| | | TC=4000K | 4800 | 5050 | 5450 | 134 | |
| | | TC=5000K | 4800 | 5050 | 5450 | 134 | |
| | | TC=5700K | 4750 | 4970 | 5350 | 132 | |
| | | TC=6000±300K | 4750 | 4970 | 5350 | 132 | |
| | | TC=6500K | 4750 | 4970 | 5350 | 132 | |
| | | IF=1050mA | 80 | — | — | — | — |
| | | IF=1050mA | — | 0.85 | — | — | W |



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|--|--|--|--|--|--|--|
| | | | | | | |
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Notes for Table

*1. Color bins are defined at IF=1050mA operation. If use different forward current, it will cause the change of chromaticity and forward voltage.

1050mA

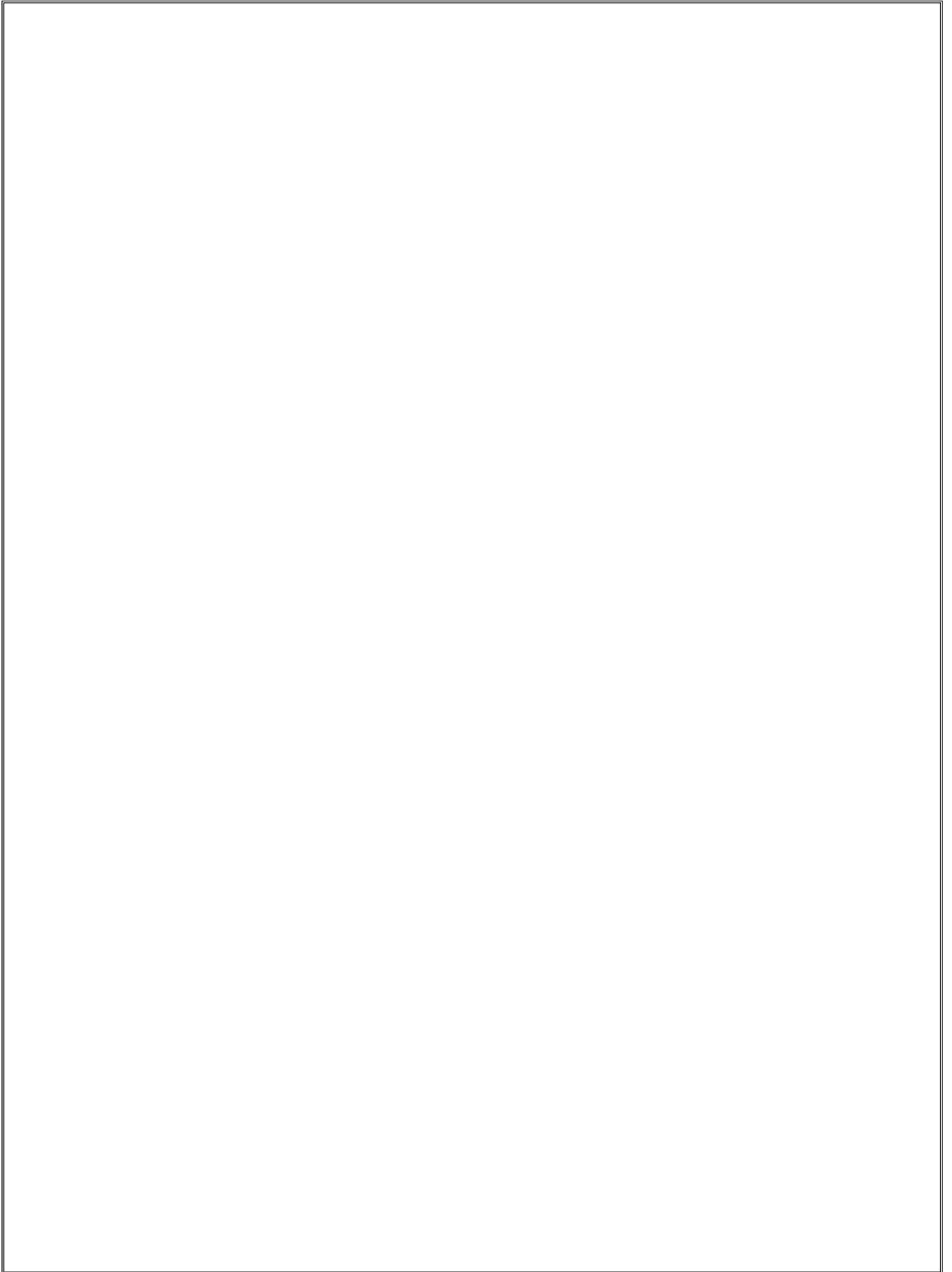
*2. The tolerance of measurement at our tester is VF±3% , v±10% and Ra±2.

±3% , ±10% ±2

3. Tolerance of ±0.005 on x,y coordinates.

±0.005

4. Color region stay within MacAdam "3-step" ellipse from the chromaticity center. but does not contain the color temperature 6000±300K. The chromaticity center refers to ANSI C78.377-2008.





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Label on ESD shielding

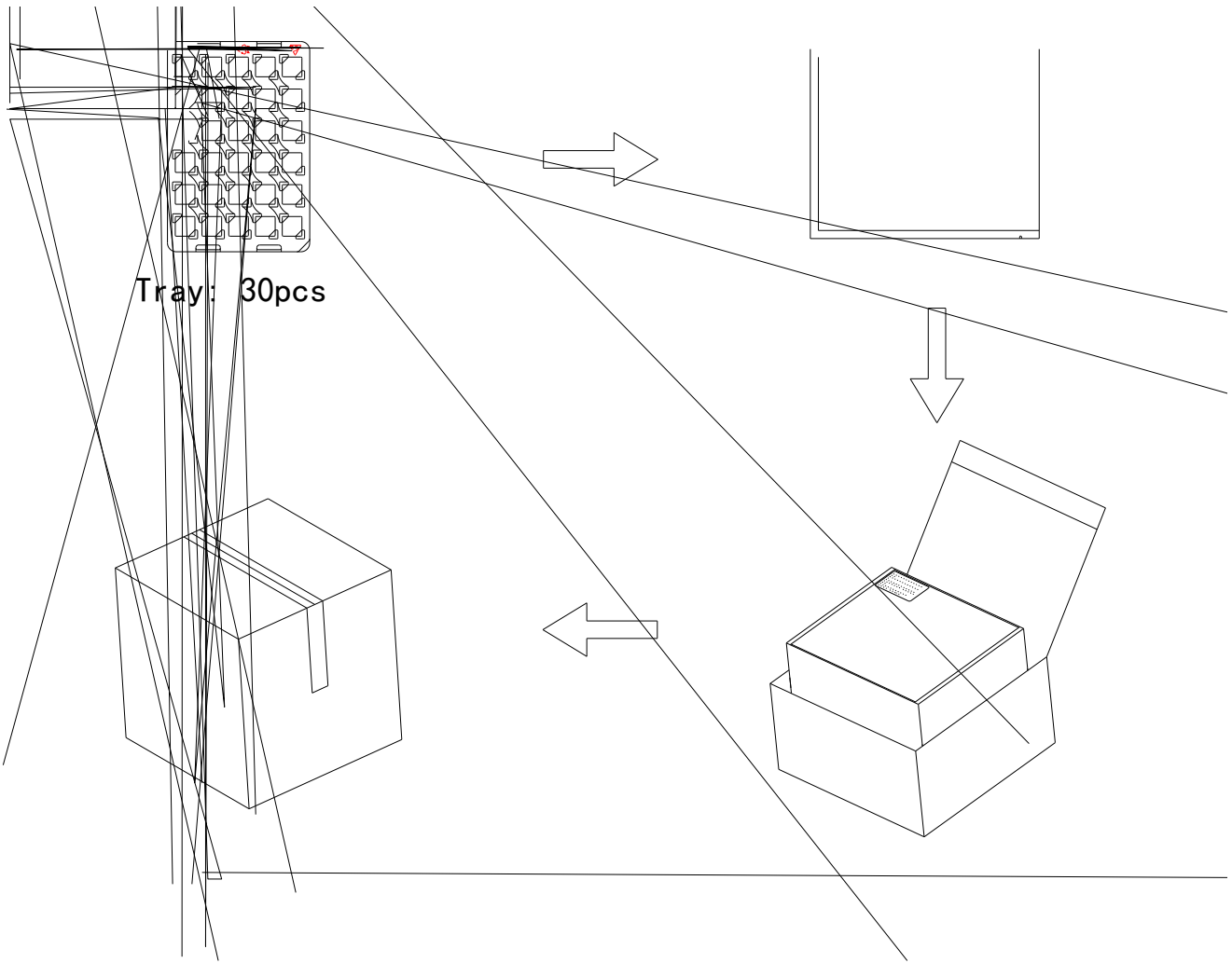
Label on box

V: Luminous Flux rank

VF: Forward voltage rank

TC: Color temperature

SDCM:





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Precaution for use ()

1. Storage

30° C

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120° C±5° C

2.

350° C



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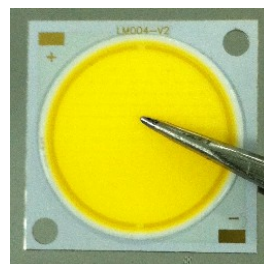
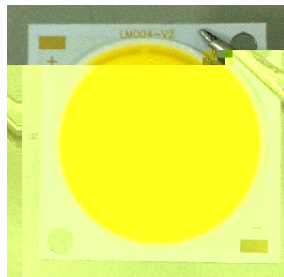
, COB recommendation colloid surface temperature control ≤ 180
85°C

180°C

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-
-
-

COB

2000PPM





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